



**NOTES**

- MATERIALS:**  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		NAME	DATE		
		ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		DRAWN	D. Abbe 8/8/11		<b>TITLE:</b>  QPQFN44-7MM-0.50MM
				CHECKED	S. Swen 8/8/11		
				ENG APPR.	S. Swen 8/8/11	<b>SIZE</b> DWG. NO. <b>REV</b> <b>B</b> 500395 <b>A</b>	
				COMMENTS:			
NEXT ASSY	USED ON	MATERIAL	SEE NOTE 1			SCALE: 10:1 WEIGHT: SHEET 1 OF 1	
		FINISH	SEE NOTE 2				
APPLICATION		DO NOT SCALE DRAWING					